

LISTING OF CLAIMS

1. (Currently amended) A process for preparing a cold seal adhesive comprising the steps of:

a) providing a curable composition comprising:

i) from 30 to 90 weight % of at least one ethylenically unsaturated compound selected from the group consisting of ethylenically unsaturated monomers and ethylenically unsaturated oligomers; wherein said monomers and oligomers have (meth)acryloxy groups;

ii) from 10 to 50 weight % of at least one liquid elastomer having no (meth)acryloxy groups; and

iii) from 0 to 60 weight % of at least one tackifier;

wherein all weight % are based on total weight of said curable composition; and

b) subjecting said curable composition to electron beam radiation to provide said cold seal adhesive.

2. (Original) The process according to claim 1 wherein said cold seal adhesive has a glass transition temperature of -30°C or less.

3. (Original) The process according to claim 1 wherein said curable composition comprises from 20 to 60 weight % of said at least one tackifier.

4. (Original) The process according to claim 1 wherein said curable composition is substantially free of photoinitiator.

5. (Currently amended) A cold seal adhesive prepared by the polymerization of a curable composition comprising:

a) from 30 to 90 weight % of at least one ethylenically unsaturated compound selected from the group consisting of ethylenically unsaturated monomers and ethylenically

unsaturated oligomers; wherein said monomers and oligomers have (meth)acryloxy groups;

b) from 10 to 50 weight % of at least one liquid elastomer having no (meth)acryloxy groups; wherein said elastomer is selected from the group consisting of polyisoprenes, polybutadienes, and polyurethanes; and

c) from 0 to 60 weight % of at least one tackifier;

wherein all weight % are based on total weight of said curable composition; and wherein said curable composition is substantially free of photoinitiator.

6. (Original) The cold seal adhesive according to claim 5 having a glass transition temperature of -30°C or less.

7. (Original) The cold seal adhesive according to claim 5 wherein said curable composition comprises from 20 to 60 weight % of said at least one tackifier.

8. (Currently amended) A curable composition comprising:

a) from 30 to 90 weight % of at least one ethylenically unsaturated compound selected from the group consisting of ethylenically unsaturated monomers and ethylenically unsaturated oligomers; wherein said monomers and oligomers have (meth)acryloxy groups;

b) from 10 to 50 weight % of at least one liquid elastomer having no (meth)acryloxy groups; wherein said elastomer is selected from the group consisting of polyisoprenes, polybutadienes, and polyurethanes; and

c) from 0 to 60 weight % of at least one tackifier;

wherein all weight % are based on total weight of said curable composition; and wherein said curable composition is substantially free of photoinitiator.

9. (Original) The curable composition according to claim 8 comprising from 20 to 60 weight % of said at least one tackifier.

10. (Original) The curable composition according to claim 8 wherein a cured polymer composition formed from said curable composition has a glass transition temperature of -30°C or less.